Version: A

2021-08-30

Specification for Approval

Customer:	_	
Model Name:		

Sı	Customer approval		
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		

Version: A

2021-08-30

Revision Record

REV NO.	REV DATE	CONTENTS	Note
Α	2021/08/30	NEW ISSUE	

Version: A

2021-08-30

Table of Contents

List	Description	Page No.
	Cover	1
	Revision Record	2
	Table of Contents	3
1	Scope	4
2	General Information	4
3	External Dimensions	5
4	Interface Description	6
5	Absolute Maximum Ratings	8
6	DC Characteristics	8
7	LVDS Signal Timing Characteristics	11
8	Backlight Characteristics	14
9	Optical Characteristics	15
10	Reliability Test Conditions and Methods	17
11	Inspection Standard	18
12	Handling Precautions	22
13	Precaution for Use	23
14	Packing Method	23



Version: A

2021-08-30

1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution

2. General Information

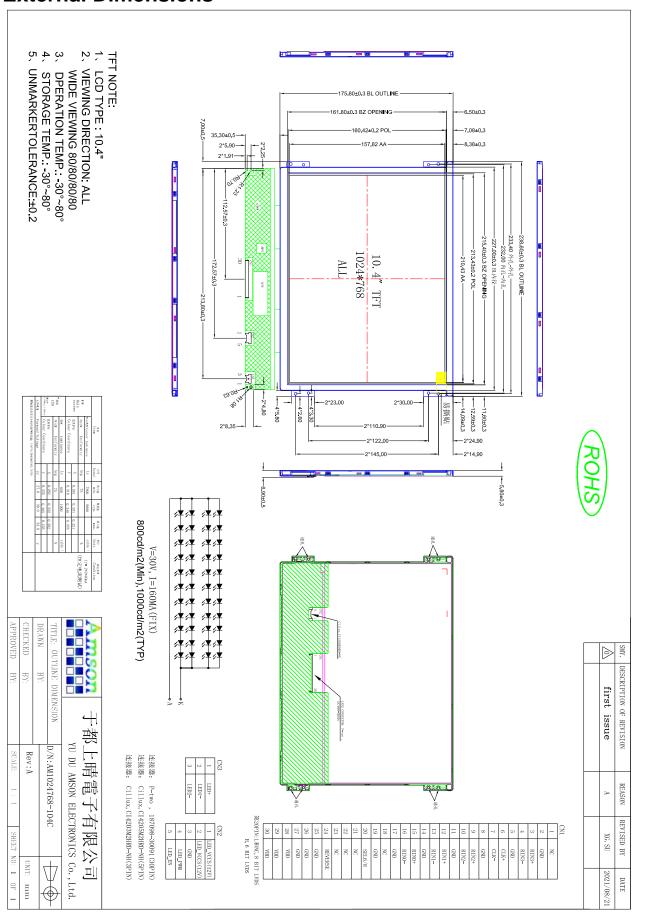
ITEM	STANDARD VALUES	UNITS
LCD type	10.4"TFT	
Dot arrangement	1024×R.G.B.×768	dots
Color filter array	RGB vertical stripe	
Display mode	Normally Black	-
Viewing Direction	80/80/80	
Module size	238.6(W) \times 175.8(H) \times 6.90(T)	mm
Active area	210.432(W)×157.824(H)	mm
Dot pitch	0.2055(W)×0.2055(H)	mm
Interface	LVDS 6/8 bit	
Operating temperature	-30 ~ +80	°C
Storage temperature	-30 ~ +80	°C



Version: A

2021-08-30

3. External Dimensions





Version: A

2021-08-30

4. Interface Description 4.1TFT LCD MODULE CN1

PIN PIN NAME DESCRIPTION Remark 1 NC Reserved as BIST function for INX test Note 1 2 GND Ground 3 RIN 3+ Positive LVDS differential data input (+) 4 RIN 3- Negative LVDS differential data input (-) 5 GND Ground 6 CLK+ Positive LVDS differential data input (-) 7 CLK- Negative LVDS differential data input (-) 8 GND Ground 9 RIN 2+ Positive LVDS differential data input (-) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (-) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RIN0 + Positive LVDS differential data input (-) 16 RIN0 - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection<	CIVI			
2 GND Ground 3 RIN 3+ Positive LVDS differential data input (+) 4 RIN 3- Negative LVDS differential data input (-) 5 GND Ground 6 CLK+ Positive LVDS differential data input (+) 7 CLK- Negative LVDS differential data input (-) 8 GND Ground 9 RIN 2+ Positive LVDS differential data input (+) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RINO + Positive LVDS differential data input (+) 16 RINO - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground 20 Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation) Note 4	PIN	PIN NAME	DESCRIPTION	Remark
3 RIN 3+ Positive LVDS differential data input (+) 4 RIN 3- Negative LVDS differential data input (-) 5 GND Ground 6 CLK+ Positive LVDS differential data input (+) 7 CLK- Negative LVDS differential data input (-) 8 GND Ground 9 RIN 2+ Positive LVDS differential data input (+) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RIN0 + Positive LVDS differential data input (+) 16 RIN0 - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground 20 SEL6/8 Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation) Note 4	1	NC	Reserved as BIST function for INX test	Note 1
4 RIN 3- Negative LVDS differential data input (-) 5 GND Ground 6 CLK+ Positive LVDS differential data input (+) 7 CLK- Negative LVDS differential data input (-) 8 GND Ground 9 RIN 2+ Positive LVDS differential data input (+) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RINO + Positive LVDS differential data input (-) 16 RINO - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground 20 SEL6/8 Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation)	2	GND	Ground	
5 GND Ground 6 CLK+ Positive LVDS differential data input (+) 7 CLK- Negative LVDS differential data input (-) 8 GND Ground 9 RIN 2+ Positive LVDS differential data input (+) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RINO + Positive LVDS differential data input (+) 16 RINO - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground 20 SEL6/8 Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation)	3	RIN 3+	Positive LVDS differential data input (+)	
6 CLK+ Positive LVDS differential data input (+) 7 CLK- Negative LVDS differential data input (-) 8 GND Ground 9 RIN 2+ Positive LVDS differential data input (+) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RINO + Positive LVDS differential data input (+) 16 RINO - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground 20 SEL6/8 SEL6/8 High : 6 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation)	4	RIN 3-	Negative LVDS differential data input (-)	
7 CLK- Negative LVDS differential data input (-) 8 GND Ground 9 RIN 2+ Positive LVDS differential data input (+) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RIN0 + Positive LVDS differential data input (+) 16 RIN0 - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground 20 SEL6/8 Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation)	5	GND	Ground	
8 GND Ground 9 RIN 2+ Positive LVDS differential data input (+) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RINO + Positive LVDS differential data input (+) 16 RINO - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground 20 SEL6/8 Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation)	6	CLK+	Positive LVDS differential data input (+)	
9 RIN 2+ Positive LVDS differential data input (+) 10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RINO + Positive LVDS differential data input (+) 16 RINO - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 20 SEL6/8 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation)	7	CLK-	Negative LVDS differential data input (-)	
10 RIN 2- Negative LVDS differential data input (-) 11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RINO + Positive LVDS differential data input (+) 16 RINO - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 20 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation)	8	GND	Ground	
11 GND Ground 12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RIN0 + Positive LVDS differential data input (+) 16 RIN0 - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 20 SEL6/8 NC Reversed as EE_WP for OTP function Note 3 21 NC Reversed as EE_SDA for OTP function Note 3 22 NC Reversed as EE_SCL for OTP function Note 3 23 NC Reverse panel function (Display rotation)	9	RIN 2+	Positive LVDS differential data input (+)	
12 RIN 1+ Positive LVDS differential data input (+) 13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RIN0 + Positive LVDS differential data input (+) 16 RIN0 - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode Note 2 1 NC Reversed as EE_WP for OTP function Note 3 2 NC Reversed as EE_SDA for OTP function Note 3 2 NC Reversed as EE_SCL for OTP function Note 3 2 REVERSE Reverse panel function (Display rotation) Note 4	10	RIN 2-	Negative LVDS differential data input (-)	
13 RIN 1- Negative LVDS differential data input (-) 14 GND Ground 15 RIN0 + Positive LVDS differential data input (+) 16 RIN0 - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 20 SEL6/8 Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation)	11	GND	Ground	
14 GND Ground 15 RIN0 + Positive LVDS differential data input (+) 16 RIN0 - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode Note 2 18 NC Reversed as EE_WP for OTP function Note 3 20 NC Reversed as EE_SDA for OTP function Note 3 NOTE Reversed as EE_SCL for OTP function Note 3 NOTE Reversed as EE_SCL for OTP function Note 3 REVERSE Reverse panel function (Display rotation)	12	RIN 1+	Positive LVDS differential data input (+)	
15 RIN0 + Positive LVDS differential data input (+) 16 RIN0 - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground 20 SEL6/8 Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation) Note 4	13	RIN 1-	Negative LVDS differential data input (-)	
16 RINO - Negative LVDS differential data input (-) 17 GND Ground 18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation) Note 4	14	GND	Ground	
17 GND Ground 18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation) Note 4	15	RIN0 +	Positive LVDS differential data input (+)	
18 NC No connection 19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode Note 2 NC Reversed as EE_WP for OTP function Note 3 NC Reversed as EE_SDA for OTP function Note 3 NC Reversed as EE_SCL for OTP function Note 3 REVERSE Reverse panel function (Display rotation) Note 4	16	RIN0 -	Negative LVDS differential data input (-)	
19 GND Ground Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode Note 2 NC Reversed as EE_WP for OTP function Note 3 NC Reversed as EE_SDA for OTP function Note 3 NC Reversed as EE_SCL for OTP function Note 3 REVERSE Reverse panel function (Display rotation) Note 4	17	GND	Ground	
Selection for 6 bits/8bit LVDS data input Low or NC : 8 bit input mode High : 6 bit input mode Note 2 NC Reversed as EE_WP for OTP function Note 3 NC Reversed as EE_SDA for OTP function Note 3 NC Reversed as EE_SCL for OTP function Note 3 REVERSE Reverse panel function (Display rotation) Note 4	18	NC	No connection	
20 SEL6/8 Low or NC : 8 bit input mode High : 6 bit input mode 21 NC Reversed as EE_WP for OTP function Note 3 22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation) Note 4	19	GND	Ground	
22 NC Reversed as EE_SDA for OTP function Note 3 23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation) Note 4	20	SEL6/8	Low or NC: 8 bit input mode	Note 2
23 NC Reversed as EE_SCL for OTP function Note 3 24 REVERSE Reverse panel function (Display rotation) Note 4	21	NC	Reversed as EE_WP for OTP function	Note 3
24 REVERSE Reverse panel function (Display rotation) Note 4	22	NC	Reversed as EE_SDA for OTP function	Note 3
	23	NC	Reversed as EE_SCL for OTP function	Note 3
05.07	24	REVERSE	Reverse panel function (Display rotation)	Note 4
25-27 GND Ground	25-27	GND	Ground	
28-30 VDD Power supply: + 3.3V	28-30	VDD	Power supply: + 3.3V	

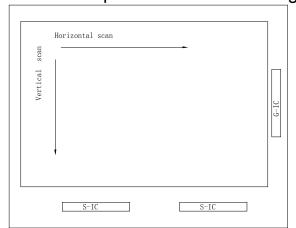
Connector:Input LVDS CONN,30pins, P-two, 187098-30091 Note:

- 1. Pin1 is reversed as BIST function for test, don't connect signal to this pin, keep floating.
- 2. SEL6/8 is used for selecting 6bit/8bit LVDS data input, L or NC: 8bit; High:6bit.
- 3. Pin21,22,23 are used as SPI interface for OTP function, don't connect any signal to these pin, and don't short them, keep floating.

Version: A

2021-08-30

4. Reverse pin is used for selecting scanning direction.



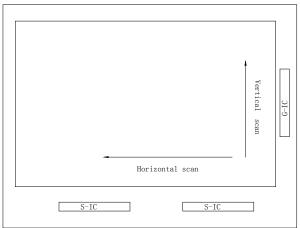


Fig. 1 Normal scan (Pin24, Reverse = Low or NC)

Fig. 2 Reverse scan (Pin24, Reverse = High)

4.2 BACKLIGHT CONVERTER (Converter connector pin)

CN₂

PIN	PIN NAME	DESCRIPTION				
1	LED_VCCS	12V input				
2	LED_VCCS	12V input				
3	GND	Ground				
4	LED_PWM	PWM				
5	11 E 1 1 E 1X1	Converter power IC Enable (Active High)				

Connector:Input BL power CONN,5pins, Cillux,CI4205M2HRD-NH 4.3 BACKLIGHT LED PIN

CN₃

PIN	PIN NAME	DESCRIPTION
1	LED+	Red wire
2	LED1-	White wire
3	LED2-	White wire

Connector:Output BL power CONN, 3pins, Cillux,CI4203M2HRD-NH



Version: A

2021-08-30

5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit	Remark
Digital Supply Voltage	VDD	-0.3	4.0	V	
VIN Voltage	VLED	-0.3	50	V	
Operating Temperature	Тор	-30	80	°C	
Storage Temperature	Тѕт	-30	80	°C	

6. DC Characteristics

6.1 Parameter

lia	Comphel		Values		Unit	Domode
Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Dowerveltage	VDD	3.0	3.3	3.6	>	
Power voltage	LED_VCCS	11	12	13	>	
Input logic high voltage	V _{IH}	0.7VDD	-	VDD	>	1
Input logic low voltage	V_{IL}	0	-	0.3VDD	>	
	I _{VDD}		385	424	mA	VDD =3.3V@frame 60 Hz, White pattern
Current for Power	I _{LED_VCCS}	-	0.52	-	А	100% PWM Duty @ VLED+ =33V, ILED=80mA*2
LED EN Control Lovel	BL On	3.0	-	5	٧	
LED_EN Control Level	BL Off	0	-	0.3	٧	
LED_PWM Control Level	PWM High Level	3.0	-	5	٧	
	PWM Low Level	0	-	0.3	٧	
LED_PWM Control Frequency	f _{PWM}	1K	-	20K	Hz	2



Version: A

2021-08-30

Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Digital Supply Voltage	VDD	2.75	3.3	3.6	٧	
VIN Voltage	LED_VCCS	-0.3	-	25	V	
Input logic high voltage	VIH	0.7*VDD	-	VDD	V	
Input logic low voltage	VIL	GND	-	0.3*VDD	V	

Note 1: Including signal: SEL6/8 & Reverse

Note 2: LED_PWM duty >10%.

6.2 BL power output

		Values				_
Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Voltage for LED backlight	V _{led}	27	30	33	V	1
Current for LED backlight	I _{led}		160		mA	2

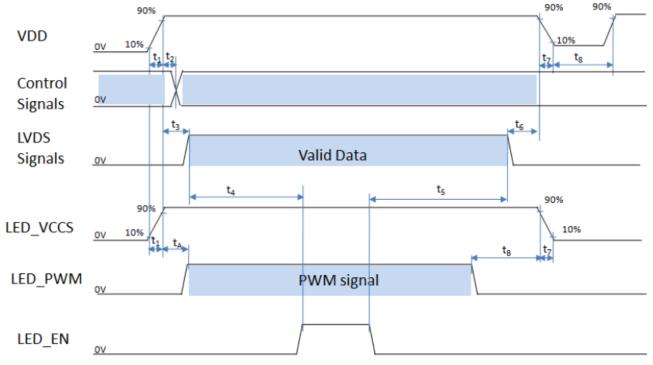
Note 1: output power LED+ OVP is 40V.

Note 2: Set BL feedback 2 channels, each channel feedback current is 80mA

6.3 Power sequence

The power sequence specifications are shown as the following table and diagram.

Cumphial	Va	alue Unit		
Symbol	Min.	Max.	Unit	
t ₁	1	20	ms	
t ₂	1	5	ms	
t ₃	10	50	ms	
t ₄	200	500	ms	
t ₅	200	500	ms	
t ₆	50	200	ms	
t ₇	0	20	ms	
t ₈	500	-	ms	
t A	t _A 0		ms	
t _B	0	50	ms	



- Note 1: Please don't plug the interface cable of on when system is turned on.
- Note 2: Please avoid floating state of the interface signal during signal invalid period.
- Note 3: It is recommended that the backlight power must be turned on after the power supply for LCD and the interface signal is valid.
- Note 4: Control signals include SEL6/8 & Reverse.

Version: A

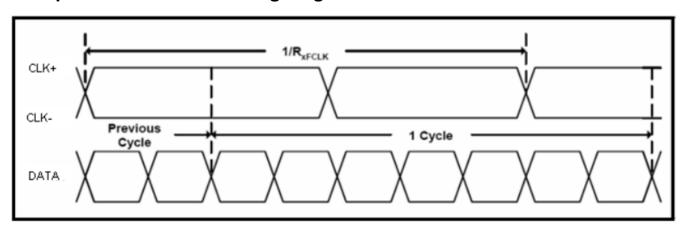
2021-08-30

7. LVDS SIGNAL TIMING CHARACTERISTICS

7.1AC Electrical characteristics

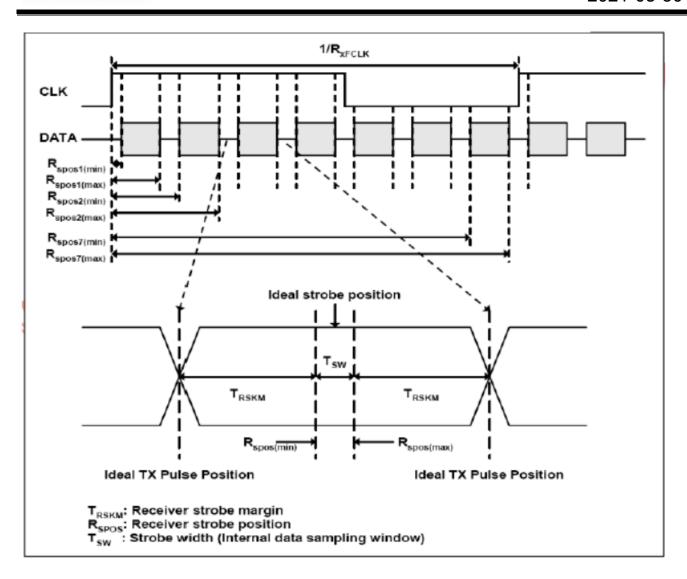
Parameter	Symbol	Min	Тур	Max	Unit s	Condition
Clock frequency	RxFCLK	26.2	51.2	71	MHz	
Input data skew margin	TRSKM	500	500	1/(2*RxFCLK)	ps	Typical value for 1024*600 resolution
Clock high time	TLVCH		4/(7xRxFCLK)		ns	VID =400mv RxVCM=1.2V RxFCLK=71MHz VDD_LVDS=3.3V
Clock low time	TLVCL		3/(7xRxFCLK)		ns	
VSD setup time	TenPLL	0	TenPLL	150	us	

7.2 Input clock and data timing diagram



Version: A

2021-08-30

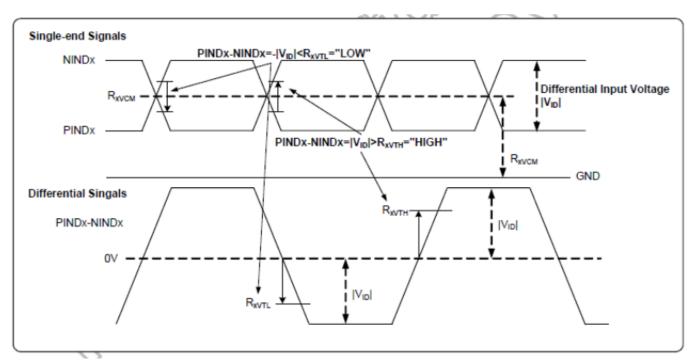


7.3 DC electrical characteristics

Damanatan	Oh al	Values			Unit	D
Parameter	Symbol	Min.	Тур.	Max.	Unit	Remark
LVDS Differential input high Threshold voltage	R _{xVTH}	-	-	+100	mV	D -1.0\/
LVDS Differential input low Threshold voltage	R _{xVTL}	-100	-	-	mV	R _{XVCM} =1.2V
Input Voltage range (Singled-end)	R _{xVIN}	0	-	VDD-1.2+ V _{ID} /2	V	
LVDS Differential input common mode voltage	R _{xVCM}	V _{ID} /2	-	VDD-1.2	٧	
LVDS Differential voltage	V _{ID}	0.2	-	0.6	V	

Version: A

2021-08-30

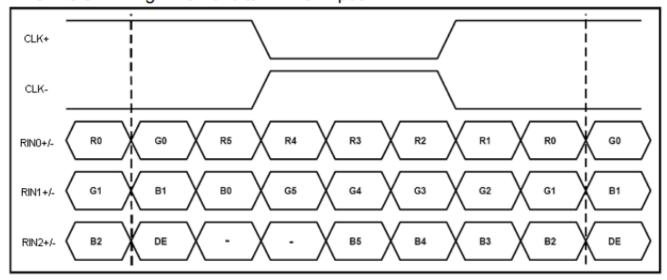


7.4 data timing

Parameter	Symbol		Spec.		
Farameter	Symbol	Min.	Тур.	Max.	Unit
DCLK frequency	fclk	52	65	71	MHz
Horizontal display area	thd		1024		DCLK
HSD period	th	1114	1344	1400	DCLK
HSD blanking	thb+thfp	90	320	376	DCLK
Vertical display area	tvd		768		T _H
VSD period	tv	778	806	845	T _H
VSD blanking	tvbp+tvfp	10	38 🛆	(//17)	T _H

7.5 LVDS data input format

SEL6/8 = "High" for 6 bits LVDS Input

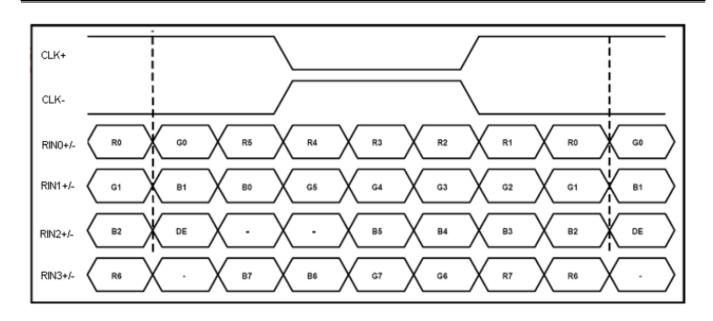


SEL6/8 = "Low" or "NC" for 8 bits LVDS Input



Version: A

2021-08-30



8. Backlight Characteristic

o. Backlight Characteristic							
Item		Symbol	MIN	TYP	MAX	UNIT	NOTE
Backlight Pow	er	LED_VCCS	-0.3	12	25	V	Ta = 25°C
Backlight Pow	er	ILED_VCCS	ı	0.5	0.8	А	LED_VCCS=12V
EN Signal Volta	VIH	IED EN	3.0		5.0	V	
ge	VIL	LED_EN	GND		0.3	V	
Luminous Intensi V		LED PWM	3.0		5.0	V	
ty for LCM	VIL	LED_PVVIVI	GND		0.3	V	
PWM Frequen	су	LED_PWM	1K	-	20K	Hz	
Lifetime			50000	-	-	Hr	
Color		White					
Average Brightness		-	800	1000	-	Cd/cm2	
Luminance unifor	mity	-	75	-	-	%	

Version: A

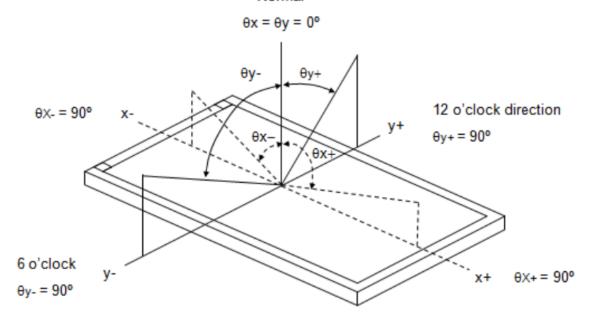
2021-08-30

9. Optical Characteristics

Item	Conditions		Min.	Тур.	Max.	Unit	Note	
	Horizontal		80	-	-			
Viewing Angle	Honzontai	θR	80	-	-	dograa	(1)	
(CR>10)	Vertical	θт	80	-	-	degree	(1)	
	vertical	θв	80	-	-			
Contrast Ratio	Center		700	1000	-	-	(2)	
Doonongo Timo	Rising			14	19	ms	(2)	
Response Time	Falling]	11	16	ms	(3)	
	Red x			0.651		-		
	Red y			0.345		-		
	Green x			0.315		-	(4)	
CF Color	Green y			0.611		-		
Chromaticity (CIE1931)	Blue x		TYP.	0.145	TYP.	-	(4)	
(=,	Blue y		-0.05	0.093	+0.05	-		
	White x			0.326		-		
	White y			0.383		-		

Note (1)Definition of Viewing Angle (θx , θy): Viewing angles are measured by BM5A

Normal



Version: A

2021-08-30

Note (2) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

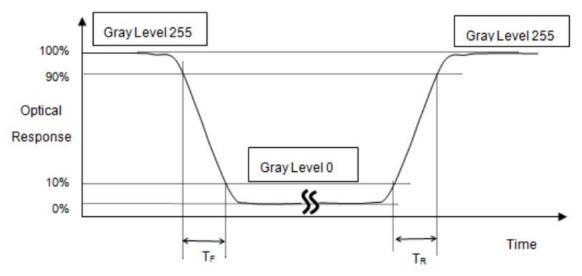
Contrast Ratio (CR) = L255 / L0

L255: Luminance of gray level 255

L 0: Luminance of gray level 0

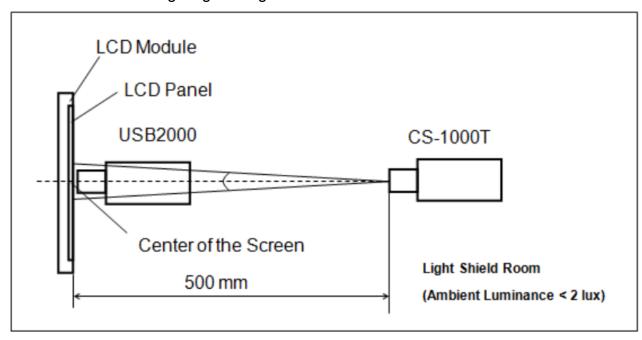
CR = CR (5), where CR (X) is corresponding to the Contrast Ratio of the point X at the figure in

Note (3) Definition of Response Time (TR, TF):



Note (4)Measurement Setup:

The LCD assembly should be stabilized at given temperature for 30 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 30 minutes in a windless room.





Version: A

2021-08-30

10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CON	NDITION			
1	High Temperature Storage	Keep in 80°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
2	Low Temperature Storage	Keep in -30°C ±5°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
3	High Temperature Operating Test	80℃*96Hrs				
4	Low Temperature Operating Test	-30℃*96Hrs				
(5)	High Temperature / High Humidity Operating Test	60 ℃ / 90% R.H ,96 hrs.				
6	High Temperature / High Humidity Storage Test	Keep in 60 ℃ / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
7	Temperature Cycling Storage Test	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$				
		Air Discharge: Apply 6 KV with 5 times Discharge for each polarity +/-	Contact Discharge: Apply 250 V with 5 times discharge for each polarity +/-			
8	ESD Test	 Temperature ambiance : 15°C ~35°C Humidity relative : 30% ~60% Energy Storage Capacitance(Cs + Cd) : 150pF±10% Discharge Resistance(Rd) : 330Ω±10% Discharge, mode of operation : Single Discharge (time between successive discharges at least 1 sec) (Tolerance if the output voltage indication : ±5%) 				
9	Vibration Test (Packaged)	 Sine wave 10~55 Hz frequency (1 min/sweep) The amplitude of vibration :1.5 mm Each direction (X, Y, Z) duration for 2 Hrs 				
10	Drop Test (Packaged)	Packing Weight (Kg) 0 ~ 45 4 45.4 ~ 90.8 90.8 ~ 454 Over 454 Drop Direction: **1 corner / 3 edges / 6	Drop Height (cm) 122 76 61 46			



Version: A

2021-08-30

11. Inspection Standard

11.1. QUALITY:

THE QUALITY OF GOODS SUPPLIED TO PURCHASER SHALL COME UP TO THE FOLLOWING STANDARD.

11.1.1. THE METHOD OF PRESERVING GOODS

AFTER DELIVERY OF GOODS FROM AMSON TO PURCHASER. PURCHASER SHALL CONTROL THE LCM AT -10 TO 40 ,AND IT MIGHT BE DESIRABLE TO KEEP AT THE NORMAL ROOM TEMPERATURE AND HUMIDITY UNTIL INCOMING INSPECTION OR THROWING INTO PROCESS LINE.

11.1.2. INCOMING INSPECTION

(A) THE METHOD OF INSPECTION

IF PURCHASER MAKE AN INCOMING INSPECTION, A SAMPLING PLAN SHALL BE APPLIED ON THE CONDITION THAT QUALITY OF ONE DELIVERY SHALL BE REGARDED AS ONE LOT.

(B) THE STANDARD OF QUALITY

ISO-2859-1 (SAME AS MIL-STD-105E), LEVEL: II

CLASS	AQL(%)
CRITICAL	0.4 %
MAJOR	0.65 %
MINOR	1.5 %

EVERY ITEM SHALL BE INSPECTED ACCORDING TO THE CLASS.

(C) MEASURE

IF AS THE RESULT OF ABOVE RECEIVING INSPECTION, A LOT OUT IS DISCOVERED. PURCHASER SHALL BE INFORM SELLER OF IT WITHIN SEVEN DAYS. BUT FIRST SHIPMENT WITHIN FOURTEEN DAYS.

11.1.3. WARRANTY POLICY

AMSON WILL PROVIDE ONE-YEAR WARRANTY FOR THE PRODUCTS ONLY IF UNDER SPECIFICATION OPERATING CONDITIONS. AMSON WILL REPLACE NEW PRODUCTS FOR THESE DEFECT PRODUCTS WHICH UNDER WARRANTY PERIOD AND BELONG TO THE RESPONSIBILITY OF AMSON.

11.2. CHECKING CONDITION

11.2.1.CHECKING DIRECTION SHALL BE IN THE 45 DEGREE AREA TO FACE THE SAMPLE.

11.2.2.CHECKER SHALL SEE OVER 300±25 mm. WITH BARE EYES FAR FROM SAMPLE **Ambient Illumination:**

Functional detection in 600nits backlight environment Appearance detection in 800~1000 Lux external environment



Version: A

2021-08-30

11.3. INSPECTION PLAN:

TI.S. INSPEC	TION I LAIN.		
CLASS	ITEM	JUDGEMENT	CLASS
	1. OUTSIDE AND INSIDE PACKAGE	"MODEL NO." , "LOT NO." AND "QUANTITY"	Minor
PACKING &		SHOULD INDICATE ON THE PACKAGE.	
INDICATE	2. MODEL MIXED AND QUANTITY	OTHER MODEL MIXEDREJECTED	Critical
		QUANTITY SHORT OR OVERREJECTED	
	3. PRODUCT INDICATION	"MODEL NO." SHOULD INDICATE ON	Major
		THE PRODUCT	
	4. DIMENSION,	ACCORDING TO SPECIFICATION OR	
ASSEMBLY	LCD GLASS SCRATCH	DRAWING.	Major
	AND SCRIBE DEFECT.		,
	5. VIEWING AREA	POLARIZER EDGE OR LCD'S SEALING LINE	Minor
		IS VISABLE IN THE VIEWING AREA	
		REJECTED	
	6. BLEMISH - BLACK SPOT -	ACCORDING TO STANDARD OF VISUAL	Minor
	WHITE SPOT IN THE LCD	INSPECTION(INSIDE VIEWING AREA)	
	AND LCD GLASS CRACKS		
	7. BLEMISH - BLACK SPOT	ACCORDING TO STANDARD OF VISUAL	Minor
APPEARANCE	WHITE SPOT AND SCRATCH	INSPECTION(INSIDE VIEWING AREA)	
	ON THE POLARIZER		
	8. BUBBLE IN POLARIZER	ACCORDING TO STANDARD OF VISUAL	Minor
		INSPECTION(INSIDE VIEWING AREA)	
	9. LCD'S RAINBOW COLOR	STRONG DEVIATION COLOR (OR NEWTON	
		RING) OF LCDREJECTED.	Minor
		OR ACCORDING TO LIMITED SAMPLE	
		(IF NEEDED, AND INSIDE VIEWING AREA)	
	10. ELECTRICAL AND OPTICAL	ACCORDING TO SPECIFICATION OR	Critical
	CHARACTERISTICS	DRAWING . (INSIDE VIEWING AREA)	
	(CONTRAST: VOP:		
	CHROMATICITY ETC)		
ELECTRICAL	11.MISSING LINE	MISSING DOT. LINE . CHARACTER	Critical
		REJECTED	
	12.SHORT CIRCUIT	NO DISPLAY - WRONG PATTERN	Critical
	WRONG PATTERN DISPLAY	DISPLAY · CURRENT CONSUMPTION	
		OUT OF SPECIFICATION REJECTED	
	13. DOT DEFECT (FOR COLOR AND TFT)	ACCORDING TO STANDARD OF VISUAL	Minor
		INSPECTION	



Version: A

2021-08-30

NO.	CLASS	ITEM	JUDGEMEN	IT			
			(A) ROUND TYPE: unit : mm.				
			DIAMETER (mm.) ACCES	PTABLE Q'TY			
			Φ ≤ 0.15	Distance≥1mm			
		BLACK AND WHITE SPOT	0.15 < Φ ≤ 0.4 3	Distance>15mm)			
		FOREIGN MATERIEL	0.4 < Φ	0			
11.4.1	4.1 MINOR		NOTE: Φ=(LENGTH+WIDTH)/2				
94184 POS (A	Interior de Partico	BLEMISH	(B) LINEAR TYPE:	unit : mm.			
		SCRATCH	LENGTH WIDTH	ACCEPTABLE Q'TY			
			W ≦0.03	Distance≥1mm			
			L ≦ 4.0 0.03 < W ≦0.05	3 (Distance>15mm)			
			0.05 < W	FOLLOW ROUND TYPE			
		5 00		unit : mm.			
			DIAMETER ACC	CEPTABLE Q'TY			
11.4.2 MINO		BUBBLE IN POLARIZER	Φ ≤ 0.2	Distance≥1mm			
	MINOR	DENT ON POLARIZER	0.2 < Φ ≤ 0.5 3	(Distance>15mm)			
			0.5 < Ф	0			
		Dot Defect		2 (Distance≥15mm) 3 (Distance≥15mm)			
11.4.3	MINOR		Pixel Define : Pixel _	Dot → of a defective dot over s one defective dot. by 5 % ND filter N ≤ 5 and unchanged in size and unchanged in size and unchanged in size in			
		Mura	Not visible thriugh 5% ND filter in 5	0% gray or judge			



Version: A

2021-08-30

NO.	CLASS	ITEM	JUDGEMENT
11.4.5	MINOR	LCD GLASS CHIPPING	X ≥ 3mm Y > S Reject
11.4.6	MINOR	LCD GLASS CHIPPING	X or Y > S Reject
11.4.7	MAJOR	LCD GLASS GLASS CRACK	Continuous burst NG Reject
11.4.8	MAJOR	LCD GLASS SCRIBE DEFECT	ACCORDING TO DIMENSION
11.4.9	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL AREA)	Y<1/2Z $Y \ge 0.5 \text{mm}_{\text{Reject}}$ $X \ge 3 \text{mm}$
11.4.10	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL SURFACE)	$Y<1/2Z$ $Y \ge 0.5 mm$ $X \ge 3 mm$
11.4.11	MINOR	LCD GLASS CHIPPING	$X\geqslant 3mm$ $Y\geqslant T\qquad \text{Reject}$ $Z\qquad \text{If touch the electrode lines,}$ the need to retain the two-thirds electrode lines



Version: A

2021-08-30

12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to power or ground, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - Usage under the maximum operating temperature, 50%Rh or less is required.



Version: A

2021-08-30

12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT, and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method TBD